

Tool ID: 322  
Tool Location: 106

## Equipment Information Sheet

# AJA-Q2

**Manager: Tom Pennell 607-254-4309**  
**Backup: Shilling Du 607-254-4907**  
**Backup: Philip Schneider 607-254-4931**

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

### SAFETY

No significant safety concerns under normal tool operation. Users should exhibit caution when moving to the rear of the tool to adjust off axis gun position.

### USAGE RESTRICTIONS

#### SCHEDULING/SIGN-UP RESTRICTIONS

*Minimum Tool Time: 30 minutes*

#### MATERIALS COMPATIBILITY CATEGORY

#### Tool Category 1E: Silicon Based Materials and Select Dielectrics

Allowed	Not Allowed
Silicon Based Materials only	No Evaporated or Sputtered Films
Si, SiC, SiO <sub>2</sub> substrates	No Metal or Organic Films
All Furnace grown or deposited films	No Glass Substrates
PECVD Films	No III/V Compound Semiconductors
Select ALD dielectrics (SiO <sub>2</sub> , SiN, HfO <sub>2</sub> , HFN)	No High Vapor pressure materials
Spin on Glass and Spin on Dopants	Organic/Biology Molecules prepared-with or without Salt buffers

**High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.**

#### Additional Material Restrictions and Exceptions

This tool is restricted to quantum computing research with associated materials. New materials will be evaluated on a case by case basis.

- No photoresist
- No high vapor pressure substrates or films
- Primary materials are Aluminum, Niobium, Tantalum and Titanium

*Last Updated: 03/27/2026*